

HSB83YP

Silicon Epitaxial Planar Diode for High Voltage Switching

REJ03G0545-0100 (Previous: ADE-208-843)

Rev.1.00

Mar 04, 2005

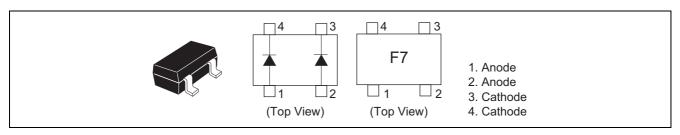
Features

- High reverse voltage. $(V_R = 250 \text{ V})$
- CMPAK- 4 package which has two devices parallel connection, is suitable for high density surface mounting.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
HSB83YP	F7	CMPAK-4	PTSP0004ZB-A (CMPAK-4)

Pin Arrangement



Absolute Maximum Ratings *2

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Peak reverse voltage	V _{RM}	300	V
Reverse voltage	V _R	250	V
Peak forward current	I _{FM}	300	mA
Non-Repetitive peak forward surge current	I _{FSM} * ¹	2	Α
Average rectified current	I ₀	100	mA
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

Notes: 1. Value at duration of 10 ms.

2. Two device total.

Electrical Characteristics *

 $(Ta = 25^{\circ}C)$

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V_{F}	_	_	1.2	V	I _F = 100 mA
Reverse current	I _{R1}	_	_	0.2	μΑ	V _R = 250 V
	I _{R2}	_	_	100		V _R = 300 V
Capacitance	С	_	_	3.0	pF	$V_R = 0 V$, $f = 1 MHz$
Reverse recovery time	t _{rr}	_		100	ns	$I_F = I_R = 30$ mA, $I_{rr} = 3$ mA, $R_L = 100$ Ω

Note: Per one device.

Main Characteristic

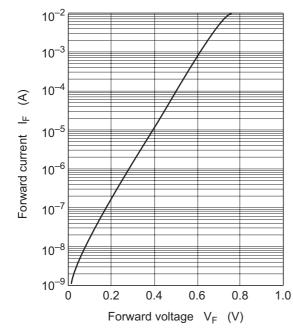


Fig.1 Forward current vs. Forward voltage

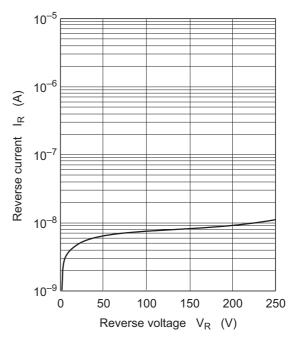
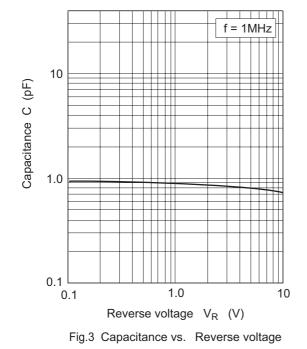
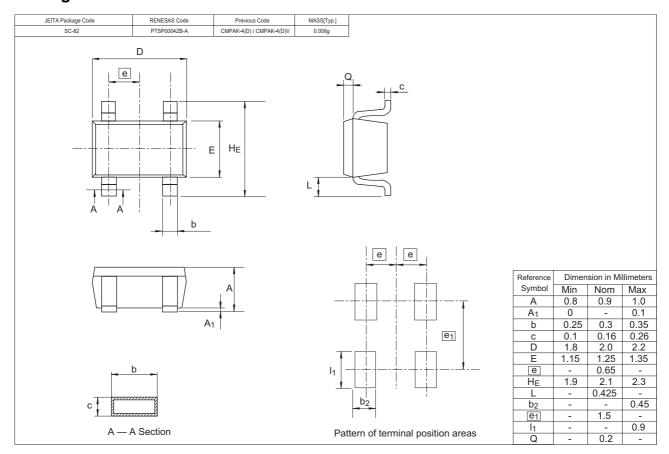


Fig.2 Reverse current vs. Reverse voltage



Package Dimensions



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